## METHOD OF FORMING A PHOTO SENSOR ON SEMICONDUCTOR WAFER WITH OVERLAPPED REGION

Appl. No.

10/065,296

Confirmation 5720

No.

Applicant

Liang-Hua Lin,

Anchor Chen

Filed

October 1, 2002

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2813

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Examiner

Kielin, Erik J

NOV 2 5 2004

Docket No. 🕔

NAUP0477USA1

Customer

27765

No.

Commissioner for Patents

P.O. Box 1450

Alexandria VA 22313-1450

## **AMENDMENT**

Sir:

5 In response to the final Office action of 08/25/2004, a request for examination is submitted continued and amendments the above-identified application are as follows:

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which 10 begins on page 4 of this paper.

Amendments to the Drawings begin on page 8 of this paper and include

both an attached replacement sheet and an annotated sheet showing changes.

Remarks/Arguments begin on page 9 of this paper.

An Appendix including amended drawing figures is attached following 5 page 21 of this paper.